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Details	
Product Status	Obsolete
Core Processor	S08
Core Size	8-Bit
Speed	40MHz
Connectivity	CANbus, I ² C, LINbus, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	25
Program Memory Size	48KB (48K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 10x12b
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	32-LQFP
Supplier Device Package	32-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mc9s08dv48amlc

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4.5.5 Sector Erase Abort

The sector erase abort operation will terminate the active sector erase operation so that other sectors are available for read and program operations without waiting for the sector erase operation to complete.

The sector erase abort command write sequence is as follows:

1. Write to any Flash address to start the command write sequence for the sector erase abort command. The address and data written are ignored.
2. Write the sector erase abort command, 0x47, to the FCMD register.
3. Clear the FCBEF flag in the FSTAT register by writing a 1 to FCBEF to launch the sector erase abort command.

If the sector erase abort command is launched resulting in the early termination of an active sector erase operation, the FACCERR flag will set once the operation completes as indicated by the FCCF flag being set. The FACCERR flag sets to inform the user that the Flash sector may not be fully erased and a new sector erase command must be launched before programming any location in that specific sector.

If the sector erase abort command is launched but the active sector erase operation completes normally, the FACCERR flag will not set upon completion of the operation as indicated by the FCCF flag being set. Therefore, if the FACCERR flag is not set after the sector erase abort command has completed, a sector being erased when the abort command was launched will be fully erased.

A flowchart to execute the sector erase abort operation is shown in [Figure 4-4](#).

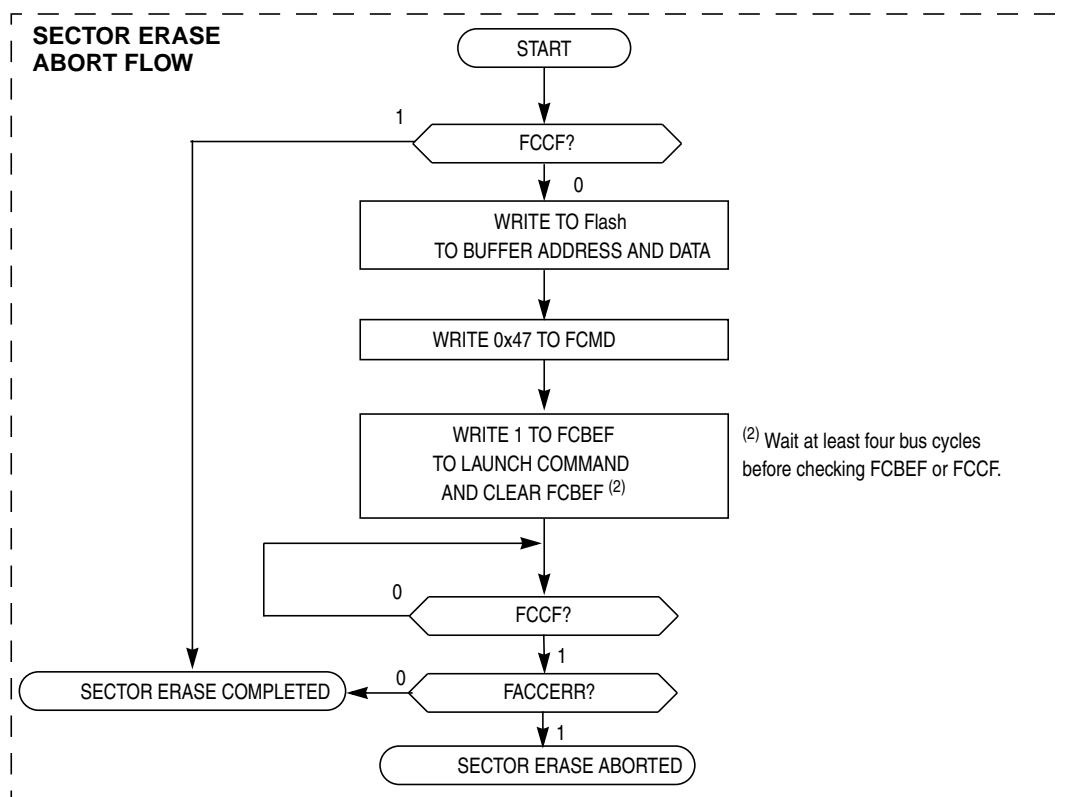


Figure 4-4. Sector Erase Abort Flowchart

6.5.1.5 Port A Drive Strength Selection Register (PTADS)

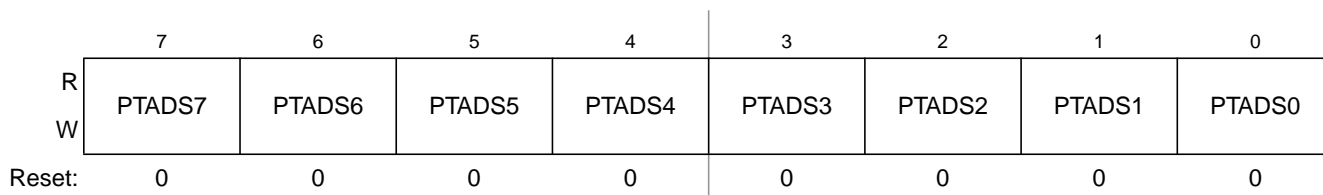


Figure 6-7. Drive Strength Selection for Port A Register (PTADS)

Table 6-5. PTADS Register Field Descriptions

Field	Description
7:0 PTADS[7:0]	Output Drive Strength Selection for Port A Bits — Each of these control bits selects between low and high output drive for the associated PTA pin. For port A pins that are configured as inputs, these bits have no effect. 0 Low output drive strength selected for port A bit n. 1 High output drive strength selected for port A bit n.

6.5.1.6 Port A Interrupt Status and Control Register (PTASC)

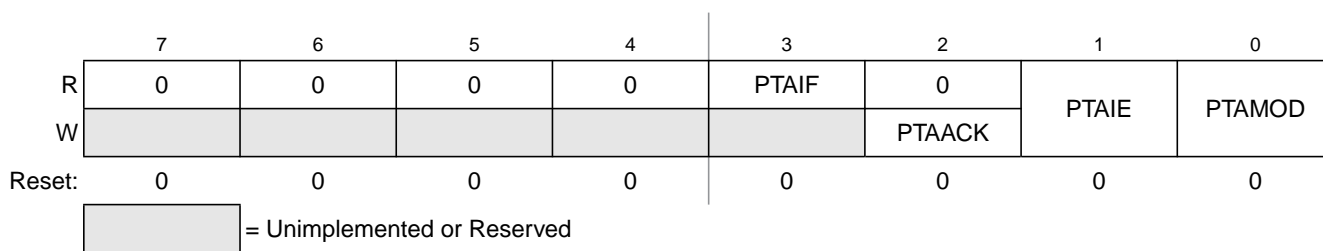


Figure 6-8. Port A Interrupt Status and Control Register (PTASC)

Table 6-6. PTASC Register Field Descriptions

Field	Description
3 PTAIF	Port A Interrupt Flag — PTAIF indicates when a port A interrupt is detected. Writes have no effect on PTAIF. 0 No port A interrupt detected. 1 Port A interrupt detected.
2 PTAACK	Port A Interrupt Acknowledge — Writing a 1 to PTAACK is part of the flag clearing mechanism. PTAACK always reads as 0.
1 PTAIE	Port A Interrupt Enable — PTAIE determines whether a port A interrupt is requested. 0 Port A interrupt request not enabled. 1 Port A interrupt request enabled.
0 PTAMOD	Port A Detection Mode — PTAMOD (along with the PTAES bits) controls the detection mode of the port A interrupt pins. 0 Port A pins detect edges only. 1 Port A pins detect both edges and levels.

6.5.3.3 Port C Pull Enable Register (PTCPE)

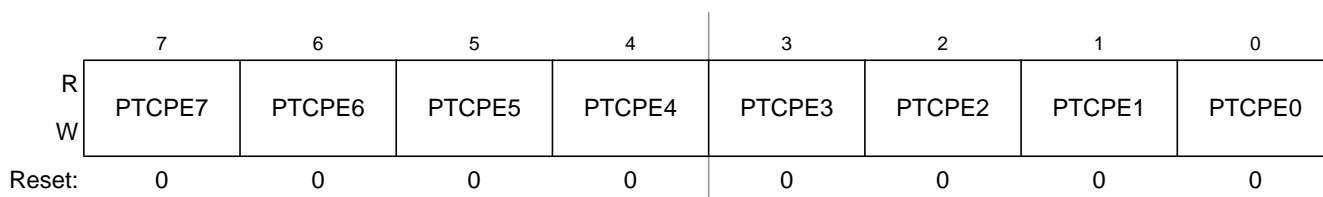


Figure 6-21. Internal Pull Enable for Port C Register (PTCPE)

Table 6-19. PTCPE Register Field Descriptions

Field	Description
7:0 PTCPE[7:0]	<p>Internal Pull Enable for Port C Bits — Each of these control bits determines if the internal pull-up device is enabled for the associated PTC pin. For port C pins that are configured as outputs, these bits have no effect and the internal pull devices are disabled.</p> <p>0 Internal pull-up device disabled for port C bit n. 1 Internal pull-up device enabled for port C bit n.</p>

NOTE

Pull-down devices only apply when using pin interrupt functions, when corresponding edge select and pin select functions are configured.

6.5.3.4 Port C Slew Rate Enable Register (PTCSE)

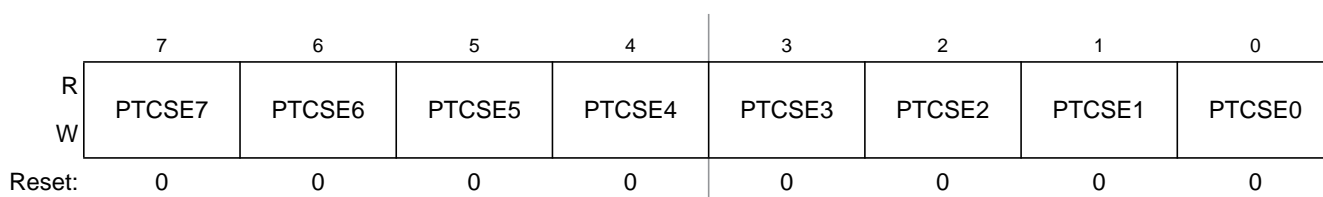


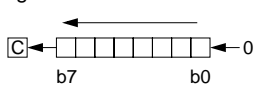
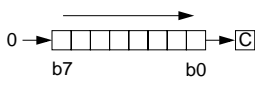
Figure 6-22. Slew Rate Enable for Port C Register (PTCSE)

Table 6-20. PTCSE Register Field Descriptions

Field	Description
7:0 PTCSE[7:0]	<p>Output Slew Rate Enable for Port C Bits — Each of these control bits determines if the output slew rate control is enabled for the associated PTC pin. For port C pins that are configured as inputs, these bits have no effect.</p> <p>0 Output slew rate control disabled for port C bit n. 1 Output slew rate control enabled for port C bit n.</p>

Note: Slew rate reset default values may differ between engineering samples and final production parts. Always initialize slew rate control to the desired value to ensure correct operation.

Table 7-2. Instruction Set Summary (Sheet 5 of 9)

Source Form	Operation	Address Mode	Object Code	Cycles	Cyc-by-Cyc Details	Affect on CCR	
						V 1 1 H	I N Z C
INC <i>opr8a</i> INCA INCX INC <i>opr8,X</i> INC ,X INC <i>opr8,SP</i>	Increment $M \leftarrow (M) + \$01$ $A \leftarrow (A) + \$01$ $X \leftarrow (X) + \$01$ $M \leftarrow (M) + \$01$ $M \leftarrow (M) + \$01$ $M \leftarrow (M) + \$01$	DIR INH INH IX1 IX SP1	3C dd 4C 5C 6C ff 7C 9E 6C ff	5 1 1 5 4 6	r#wpp p p r#wpp r#wp pr#wpp		\uparrow 1 1 - - \uparrow \downarrow \downarrow -
JMP <i>opr8a</i> JMP <i>opr16a</i> JMP <i>opr16,X</i> JMP <i>opr8,X</i> JMP ,X	Jump PC \leftarrow Jump Address	DIR EXT IX2 IX1 IX	BC dd CC hh ll DC ee ff EC ff FC	3 4 4 3 3	ppp pppp pppp ppp ppp	- 1 1 - - - - -	
JSR <i>opr8a</i> JSR <i>opr16a</i> JSR <i>opr16,X</i> JSR <i>opr8,X</i> JSR ,X	Jump to Subroutine PC \leftarrow (PC) + <i>n</i> (<i>n</i> = 1, 2, or 3) Push (PCL); SP \leftarrow (SP) - \$0001 Push (PCH); SP \leftarrow (SP) - \$0001 PC \leftarrow Unconditional Address	DIR EXT IX2 IX1 IX	BD dd CD hh ll DD ee ff ED ff FD	5 6 6 5 5	ssppp psppp psppp ssppp ssppp	- 1 1 - - - - -	
LDA # <i>opr8i</i> LDA <i>opr8a</i> LDA <i>opr16a</i> LDA <i>opr16,X</i> LDA <i>opr8,X</i> LDA ,X LDA <i>opr16,SP</i> LDA <i>opr8,SP</i>	Load Accumulator from Memory $A \leftarrow (M)$	IMM DIR EXT IX2 IX1 IX SP2 SP1	A6 ii B6 dd C6 hh ll D6 ee ff E6 ff F6 9E D6 ee ff 9E E6 ff	2 3 4 4 3 3 5 4	pp rpp prpp prpp rpp rfp pprpp prpp	0 1 1 - - \uparrow \downarrow \downarrow -	
LDHX # <i>opr16i</i> LDHX <i>opr8a</i> LDHX <i>opr16a</i> LDHX ,X LDHX <i>opr16,X</i> LDHX <i>opr8,X</i> LDHX <i>opr8,SP</i>	Load Index Register (H:X) $H:X \leftarrow (M:M + \$0001)$	IMM DIR EXT IX IX2 IX1 SP1	45 jj kk 55 dd 32 hh ll 9E AE 9E BE ee ff 9E CE ff 9E FE ff	3 4 5 5 6 5 5	ppp rrpp prpp prfp pprpp prpp prpp	0 1 1 - - \uparrow \downarrow \downarrow -	
LDX # <i>opr8i</i> LDX <i>opr8a</i> LDX <i>opr16a</i> LDX <i>opr16,X</i> LDX <i>opr8,X</i> LDX ,X LDX <i>opr16,SP</i> LDX <i>opr8,SP</i>	Load X (Index Register Low) from Memory $X \leftarrow (M)$	IMM DIR EXT IX2 IX1 IX SP2 SP1	AE ii BE dd CE hh ll DE ee ff EE ff FE 9E DE ee ff 9E EE ff	2 3 4 4 3 3 5 4	pp rpp prpp prpp rpp rfp pprpp prpp	0 1 1 - - \uparrow \downarrow \downarrow -	
LSL <i>opr8a</i> LSLA LSLX LSL <i>opr8,X</i> LSL ,X LSL <i>opr8,SP</i>	Logical Shift Left  (Same as ASL)	DIR INH INH IX1 IX SP1	38 dd 48 58 68 ff 78 9E 68 ff	5 1 1 5 4 6	r#wpp p p r#wpp r#wp pr#wpp	\uparrow 1 1 - - \uparrow \downarrow \downarrow \downarrow	
LSR <i>opr8a</i> LSRA LSRX LSR <i>opr8,X</i> LSR ,X LSR <i>opr8,SP</i>	Logical Shift Right 	DIR INH INH IX1 IX SP1	34 dd 44 54 64 ff 74 9E 64 ff	5 1 1 5 4 6	r#wpp p p r#wpp r#wp pr#wpp	\uparrow 1 1 - - 0 \downarrow \downarrow	

external crystal and a maximum reference divider factor of 128, the resulting frequency of the reference clock for the FLL is 62.5 kHz (greater than the 39.0625 kHz maximum allowed).

Care must be taken in the software to minimize the amount of time spent in this state where the FLL is operating in this condition.

The following code sequence describes how to move from FEI mode to PEE mode until the 8 MHz crystal reference frequency is set to achieve a bus frequency of 8 MHz. Because the MCG is in FEI mode out of reset, this example also shows how to initialize the MCG for PEE mode out of reset. First, the code sequence will be described. Then a flowchart will be included which illustrates the sequence.

1. First, FEI must transition to FBE mode:
 - a) MCGC2 = 0x36 (%00110110)
 - BDIV (bits 7 and 6) set to %00, or divide-by-1
 - RANGE (bit 5) set to 1 because the frequency of 8 MHz is within the high frequency range
 - HGO (bit 4) set to 1 to configure external oscillator for high gain operation
 - EREFS (bit 2) set to 1, because a crystal is being used
 - ERCLKEN (bit 1) set to 1 to ensure the external reference clock is active
 - b) Loop until OSCINIT (bit 1) in MCGSC is 1, indicating the crystal selected by the EREFS bit has been initialized.
 - c) Block Interrupts (If applicable by setting the interrupt bit in the CCR).
 - d) MCGC1 = 0xB8 (%10111000)
 - CLKS (bits 7 and 6) set to %10 in order to select external reference clock as system clock source
 - RDIV (bits 5-3) set to %111, or divide-by-128.

NOTE

8 MHz / 128 = 62.5 kHz which is greater than the 31.25 kHz to 39.0625 kHz range required by the FLL. Therefore after the transition to FBE is complete, software must progress through to BLPE mode immediately by setting the LP bit in MCGC2.

- IREFS (bit 2) cleared to 0, selecting the external reference clock
 - e) Loop until IREFST (bit 4) in MCGSC is 0, indicating the external reference is the current source for the reference clock
 - f) Loop until CLKST (bits 3 and 2) in MCGSC are %10, indicating that the external reference clock is selected to feed MCGOUT
2. Then, FBE mode transitions into BLPE mode:
 - a) MCGC2 = 0x3E (%00111110)
 - LP (bit 3) in MCGC2 to 1 (BLPE mode entered)

NOTE

There must be no extra steps (including interrupts) between steps 1d and 2a.

- b) Enable Interrupts (if applicable by clearing the interrupt bit in the CCR).

9.3 Memory Map/Register Definition

The ACMP includes one register:

- An 8-bit status and control register

Refer to the direct-page register summary in the memory section of this document for the absolute address assignments for the ACMP register. This section refers to register and control bits only by their names and relative address offsets.

Some MCUs may have more than one ACMP, so register names include placeholder characters (x) to identify which ACMP is being referenced.

Table 9-2. ACMP Register Summary

Name		7	6	5	4	3	2	1	0
ACMPxSC	R	ACME	ACBGS	ACF	ACIE	ACO	ACOPE	ACMOD	
	W								

9.3.1 ACMPx Status and Control Register (ACMPxSC)

ACMPxSC contains the status flag and control bits used to enable and configure the ACMP.

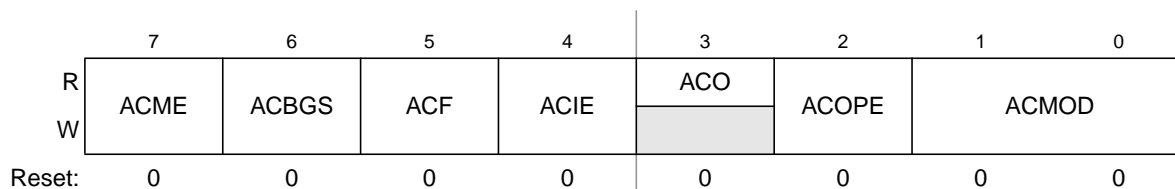


Figure 9-3. ACMPx Status and Control Register (ACMPxSC)

Table 9-3. ACMPxSC Field Descriptions

Field	Description
7 ACME	Analog Comparator Module Enable. Enables the ACMP module. 0 ACMP not enabled 1 ACMP is enabled
6 ACBGS	Analog Comparator Bandgap Select. Selects between the bandgap reference voltage or the ACMPx+ pin as the input to the non-inverting input of the analog comparator. 0 External pin ACMPx+ selected as non-inverting input to comparator 1 Internal reference select as non-inverting input to comparator
5 ACF	Analog Comparator Flag. ACF is set when a compare event occurs. Compare events are defined by ACMOD. ACF is cleared by writing a one to it. 0 Compare event has not occurred 1 Compare event has occurred
4 ACIE	Analog Comparator Interrupt Enable. Enables the interrupt from the ACMP. When ACIE is set, an interrupt is asserted when ACF is set. 0 Interrupt disabled 1 Interrupt enabled

11.7 Initialization/Application Information

Module Initialization (Slave)

1. Write: IICC2
 - to enable or disable general call
 - to select 10-bit or 7-bit addressing mode
2. Write: IICA
 - to set the slave address
3. Write: IICC1
 - to enable IIC and interrupts
4. Initialize RAM variables (IICEN = 1 and IICIE = 1) for transmit data
5. Initialize RAM variables used to achieve the routine shown in [Figure 11-12](#)

Module Initialization (Master)

1. Write: IICF
 - to set the IIC baud rate (example provided in this chapter)
2. Write: IICC1
 - to enable IIC and interrupts
3. Initialize RAM variables (IICEN = 1 and IICIE = 1) for transmit data
4. Initialize RAM variables used to achieve the routine shown in [Figure 11-12](#)
5. Write: IICC1
 - to enable TX
6. Write: IICC1
 - to enable MST (master mode)
7. Write: IICD
 - with the address of the target slave. (The lsb of this byte determines whether the communication is master receive or transmit.)

Module Use

The routine shown in [Figure 11-12](#) can handle both master and slave IIC operations. For slave operation, an incoming IIC message that contains the proper address begins IIC communication. For master operation, communication must be initiated by writing to the IICD register.

Register Model

IICA	AD[7:1]							0
	When addressed as a slave (in slave mode), the module responds to this address							
IICF	MULT			ICR				
	Baud rate = BUSCLK / (2 x MULT x (SCL DIVIDER))							
IICC1	IICEN	IICIE	MST	TX	TXAK	RSTA	0	0
	Module configuration							
IICS	TCF	IAAS	BUSY	ARBL	0	SRW	IICIF	RXAK
	Module status flags							
IICD	DATA							
	Data register; Write to transmit IIC data read to read IIC data							
IICC2	GCAEN	ADEXT	0	0	0	AD10	AD9	AD8
	Address configuration							

Figure 11-11. IIC Module Quick Start

Table 12-1. CANCTL0 Register Field Descriptions (continued)

Field	Description
1 SLPRQ ⁵	<p>Sleep Mode Request — This bit requests the MSCAN to enter sleep mode, which is an internal power saving mode (see Section 12.5.5.4, “MSCAN Sleep Mode”). The sleep mode request is serviced when the CAN bus is idle, i.e., the module is not receiving a message and all transmit buffers are empty. The module indicates entry to sleep mode by setting SLPK = 1 (see Section 12.3.2, “MSCAN Control Register 1 (CANCTL1)”). SLPRQ cannot be set while the WUPIF flag is set (see Section 12.3.4.1, “MSCAN Receiver Flag Register (CANRFLG)”). Sleep mode will be active until SLPRQ is cleared by the CPU or, depending on the setting of WUPE, the MSCAN detects activity on the CAN bus and clears SLPRQ itself.</p> <p>0 Running — The MSCAN functions normally 1 Sleep mode request — The MSCAN enters sleep mode when CAN bus idle</p>
0 INITRQ ^{6,7}	<p>Initialization Mode Request — When this bit is set by the CPU, the MSCAN skips to initialization mode (see Section 12.5.5.5, “MSCAN Initialization Mode”). Any ongoing transmission or reception is aborted and synchronization to the CAN bus is lost. The module indicates entry to initialization mode by setting INITAK = 1 (Section 12.3.2, “MSCAN Control Register 1 (CANCTL1)”).</p> <p>The following registers enter their hard reset state and restore their default values: CANCTL0⁸, CANRFLG⁹, CANRIER¹⁰, CANTFLG, CANTIER, CANTARQ, CANTAACK, and CANTBSEL.</p> <p>The registers CANCTL1, CANBTR0, CANBTR1, CANIDAC, CANIDAR0-7, and CANIDMR0-7 can only be written by the CPU when the MSCAN is in initialization mode (INITRQ = 1 and INITAK = 1). The values of the error counters are not affected by initialization mode.</p> <p>When this bit is cleared by the CPU, the MSCAN restarts and then tries to synchronize to the CAN bus. If the MSCAN is not in bus-off state, it synchronizes after 11 consecutive recessive bits on the CAN bus; if the MSCAN is in bus-off state, it continues to wait for 128 occurrences of 11 consecutive recessive bits.</p> <p>Writing to other bits in CANCTL0, CANRFLG, CANRIER, CANTFLG, or CANTIER must be done only after initialization mode is exited, which is INITRQ = 0 and INITAK = 0.</p> <p>0 Normal operation 1 MSCAN in initialization mode</p>

- ¹ The MSCAN must be in normal mode for this bit to become set.
- ² See the Bosch CAN 2.0A/B specification for a detailed definition of transmitter and receiver states.
- ³ In order to protect from accidentally violating the CAN protocol, the TXCAN pin is immediately forced to a recessive state when the CPU enters wait (CSWAI = 1) or stop mode (see Section 12.5.5.2, “Operation in Wait Mode” and Section 12.5.5.3, “Operation in Stop Mode”).
- ⁴ The CPU has to make sure that the WUPE bit and the WUPIE wake-up interrupt enable bit (see Section 12.3.5, “MSCAN Receiver Interrupt Enable Register (CANRIER)”) is enabled, if the recovery mechanism from stop or wait is required.
- ⁵ The CPU cannot clear SLPRQ before the MSCAN has entered sleep mode (SLPRQ = 1 and SLPK = 1).
- ⁶ The CPU cannot clear INITRQ before the MSCAN has entered initialization mode (INITRQ = 1 and INITAK = 1).
- ⁷ In order to protect from accidentally violating the CAN protocol, the TXCAN pin is immediately forced to a recessive state when the initialization mode is requested by the CPU. Thus, the recommended procedure is to bring the MSCAN into sleep mode (SLPRQ = 1 and SLPK = 1) before requesting initialization mode.
- ⁸ Not including WUPE, INITRQ, and SLPRQ.
- ⁹ TSTAT1 and TSTAT0 are not affected by initialization mode.
- ¹⁰ RSTAT1 and RSTAT0 are not affected by initialization mode.

NOTE

The CANRFLG register is held in the reset state¹ when the initialization mode is active (INITRQ = 1 and INITAK = 1). This register is writable again as soon as the initialization mode is exited (INITRQ = 0 and INITAK = 0).

Read: Anytime

Write: Anytime when out of initialization mode, except RSTAT[1:0] and TSTAT[1:0] flags which are read-only; write of 1 clears flag; write of 0 is ignored.

Table 12-9. CANRFLG Register Field Descriptions

Field	Description
7 WUPIF	Wake-Up Interrupt Flag — If the MSCAN detects CAN bus activity while in sleep mode (see Section 12.5.5.4, “MSCAN Sleep Mode,”) and WUPE = 1 in CANTCTL0 (see Section 12.3.1, “MSCAN Control Register 0 (CANCTL0)”), the module will set WUPIF. If not masked, a wake-up interrupt is pending while this flag is set. 0 No wake-up activity observed while in sleep mode 1 MSCAN detected activity on the CAN bus and requested wake-up
6 CSCIF	CAN Status Change Interrupt Flag — This flag is set when the MSCAN changes its current CAN bus status due to the actual value of the transmit error counter (TEC) and the receive error counter (REC). An additional 4-bit (RSTAT[1:0], TSTAT[1:0]) status register, which is split into separate sections for TEC/REC, informs the system on the actual CAN bus status (see Section 12.3.5, “MSCAN Receiver Interrupt Enable Register (CANRIER)”). If not masked, an error interrupt is pending while this flag is set. CSCIF provides a blocking interrupt. That guarantees that the receiver/transmitter status bits (RSTAT/TSTAT) are only updated when no CAN status change interrupt is pending. If the TECs/RECs change their current value after the CSCIF is asserted, which would cause an additional state change in the RSTAT/TSTAT bits, these bits keep their status until the current CSCIF interrupt is cleared again. 0 No change in CAN bus status occurred since last interrupt 1 MSCAN changed current CAN bus status
5:4 RSTAT[1:0]	Receiver Status Bits — The values of the error counters control the actual CAN bus status of the MSCAN. As soon as the status change interrupt flag (CSCIF) is set, these bits indicate the appropriate receiver related CAN bus status of the MSCAN. The coding for the bits RSTAT1, RSTAT0 is: 00 RxOK: 0 ≤ receive error counter ≤ 96 01 RxWRN: 96 < receive error counter ≤ 127 10 RxERR: 127 < receive error counter 11 Bus-off ¹ : transmit error counter > 255
3:2 TSTAT[1:0]	Transmitter Status Bits — The values of the error counters control the actual CAN bus status of the MSCAN. As soon as the status change interrupt flag (CSCIF) is set, these bits indicate the appropriate transmitter related CAN bus status of the MSCAN. The coding for the bits TSTAT1, TSTAT0 is: 00 TxOK: 0 ≤ transmit error counter ≤ 96 01 TxWRN: 96 < transmit error counter ≤ 127 10 TxERR: 127 < transmit error counter ≤ 255 11 Bus-Off: transmit error counter > 255

1. The RSTAT[1:0], TSTAT[1:0] bits are not affected by initialization mode.

12.5.3.2 Protocol Violation Protection

The MSCAN protects the user from accidentally violating the CAN protocol through programming errors. The protection logic implements the following features:

- The receive and transmit error counters cannot be written or otherwise manipulated.
- All registers which control the configuration of the MSCAN cannot be modified while the MSCAN is on-line. The MSCAN has to be in Initialization Mode. The corresponding INITRQ/INITAK handshake bits in the CANCTL0/CANCTL1 registers (see Section 12.3.1, “MSCAN Control Register 0 (CANCTL0)”) serve as a lock to protect the following registers:
 - MSCAN control 1 register (CANCTL1)
 - MSCAN bus timing registers 0 and 1 (CANBTR0, CANBTR1)
 - MSCAN identifier acceptance control register (CANIDAC)
 - MSCAN identifier acceptance registers (CANIDAR0–CANIDAR7)
 - MSCAN identifier mask registers (CANIDMR0–CANIDMR7)
- The TXCAN pin is immediately forced to a recessive state when the MSCAN goes into the power down mode or initialization mode (see Section 12.5.5.6, “MSCAN Power Down Mode,” and Section 12.5.5.5, “MSCAN Initialization Mode”).
- The MSCAN enable bit (CANE) is writable only once in normal system operation modes, which provides further protection against inadvertently disabling the MSCAN.

12.5.3.3 Clock System

Figure 12-42 shows the structure of the MSCAN clock generation circuitry.

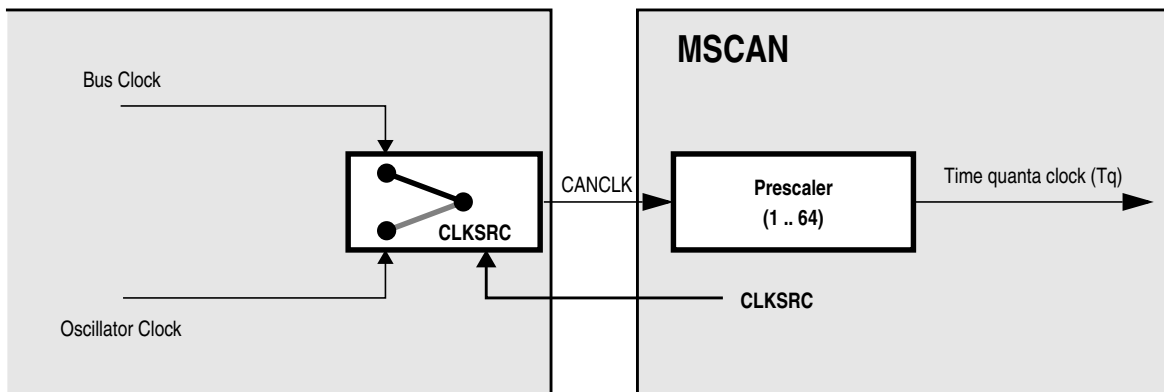


Figure 12-42. MSCAN Clocking Scheme

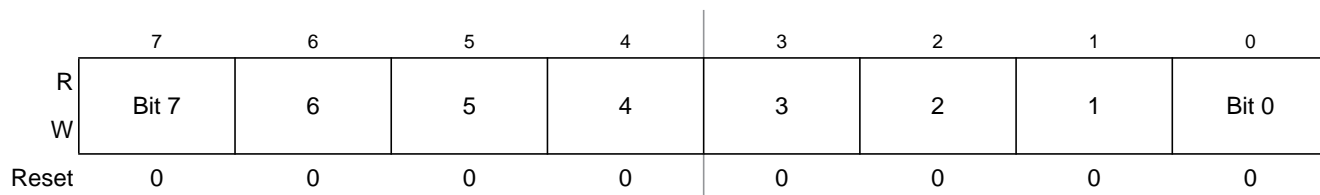
The clock source bit (CLKSRC) in the CANCTL1 register (12.3.2/-224) defines whether the internal CANCLK is connected to the output of a crystal oscillator (oscillator clock) or to the bus clock.

The clock source has to be chosen such that the tight oscillator tolerance requirements (up to 0.4%) of the CAN protocol are met. Additionally, for high CAN bus rates (1 Mbps), a 45% to 55% duty cycle of the clock is required.

Table 13-7. SPIS Register Field Descriptions

Field	Description
7 SPRF	SPI Read Buffer Full Flag — SPRF is set at the completion of an SPI transfer to indicate that received data may be read from the SPI data register (SPID). SPRF is cleared by reading SPRF while it is set, then reading the SPI data register. 0 No data available in the receive data buffer 1 Data available in the receive data buffer
5 SPTEF	SPI Transmit Buffer Empty Flag — This bit is set when there is room in the transmit data buffer. It is cleared by reading SPIS with SPTEF set, followed by writing a data value to the transmit buffer at SPID. SPIS must be read with SPTEF = 1 before writing data to SPID or the SPID write will be ignored. SPTEF generates an SPTEF CPU interrupt request if the SPTIE bit in the SPIC1 is also set. SPTEF is automatically set when a data byte transfers from the transmit buffer into the transmit shift register. For an idle SPI (no data in the transmit buffer or the shift register and no transfer in progress), data written to SPID is transferred to the shifter almost immediately so SPTEF is set within two bus cycles allowing a second 8-bit data value to be queued into the transmit buffer. After completion of the transfer of the value in the shift register, the queued value from the transmit buffer will automatically move to the shifter and SPTEF will be set to indicate there is room for new data in the transmit buffer. If no new data is waiting in the transmit buffer, SPTEF simply remains set and no data moves from the buffer to the shifter. 0 SPI transmit buffer not empty 1 SPI transmit buffer empty
4 MODF	Master Mode Fault Flag — MODF is set if the SPI is configured as a master and the slave select input goes low, indicating some other SPI device is also configured as a master. The \overline{SS} pin acts as a mode fault error input only when MSTR = 1, MODFEN = 1, and SSOE = 0; otherwise, MODF will never be set. MODF is cleared by reading MODF while it is 1, then writing to SPI control register 1 (SPIC1). 0 No mode fault error 1 Mode fault error detected

13.4.5 SPI Data Register (SPID)


Figure 13-9. SPI Data Register (SPID)

Reads of this register return the data read from the receive data buffer. Writes to this register write data to the transmit data buffer. When the SPI is configured as a master, writing data to the transmit data buffer initiates an SPI transfer.

Data should not be written to the transmit data buffer unless the SPI transmit buffer empty flag (SPTEF) is set, indicating there is room in the transmit buffer to queue a new transmit byte.

Data may be read from SPID any time after SPRF is set and before another transfer is finished. Failure to read the data out of the receive data buffer before a new transfer ends causes a receive overrun condition and the data from the new transfer is lost.

in LSBFE. Both variations of SPSCCK polarity are shown, but only one of these waveforms applies for a specific transfer, depending on the value in CPOL. The SAMPLE IN waveform applies to the MOSI input of a slave or the MISO input of a master. The MOSI waveform applies to the MOSI output pin from a master and the MISO waveform applies to the MISO output from a slave. The \overline{SS} OUT waveform applies to the slave select output from a master (provided MODFEN and SSOE = 1). The master \overline{SS} output goes to active low at the start of the first bit time of the transfer and goes back high one-half SPSCCK cycle after the end of the eighth bit time of the transfer. The \overline{SS} IN waveform applies to the slave select input of a slave.

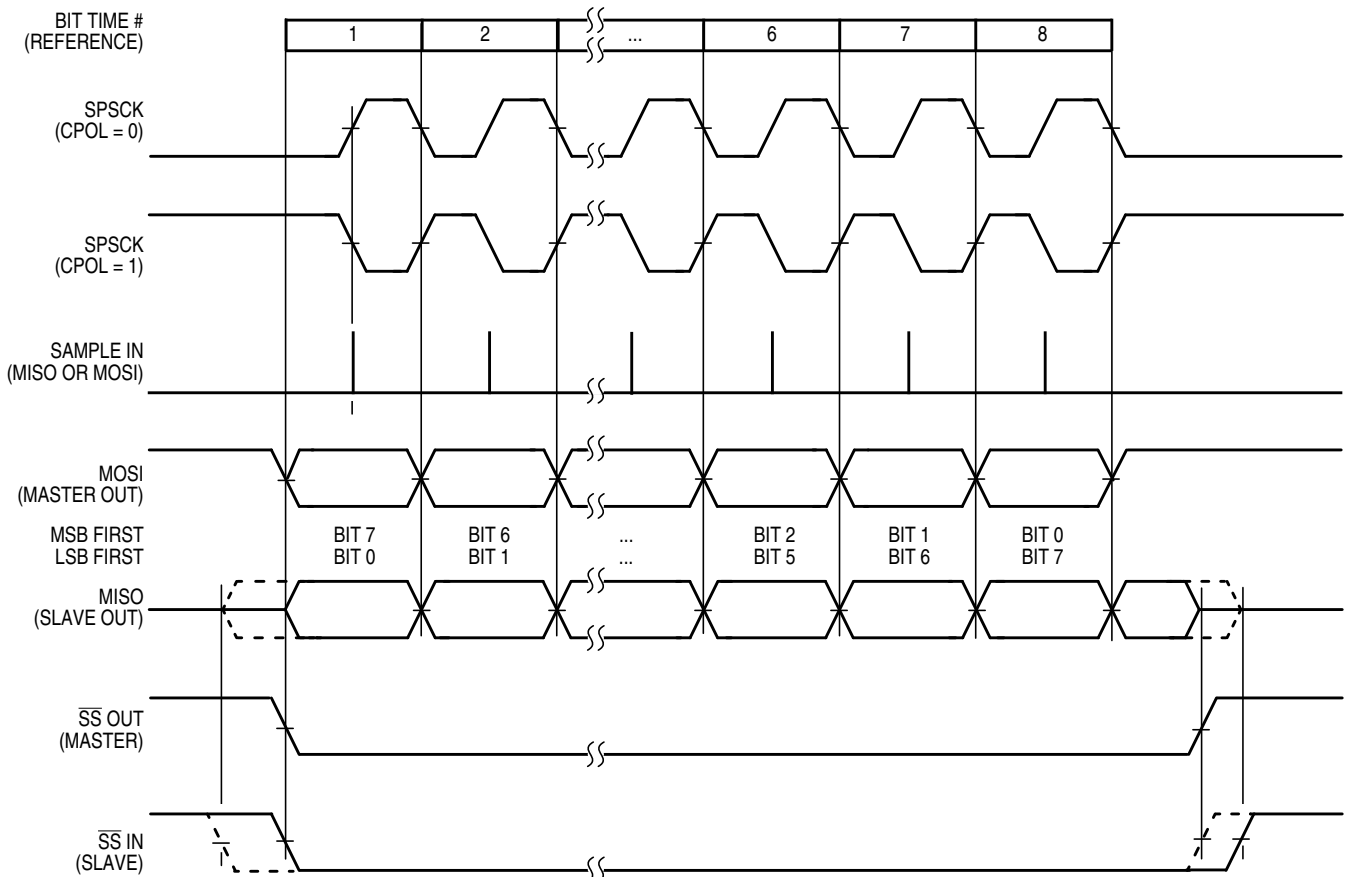


Figure 13-11. SPI Clock Formats (CPHA = 0)

When CPHA = 0, the slave begins to drive its MISO output with the first data bit value (MSB or LSB depending on LSBFE) when \overline{SS} goes to active low. The first SPSCCK edge causes both the master and the slave to sample the data bit values on their MISO and MOSI inputs, respectively. At the second SPSCCK edge, the SPI shifter shifts one bit position which shifts in the bit value that was just sampled and shifts the second data bit value out the other end of the shifter to the MOSI and MISO outputs of the master and slave, respectively. When CPHA = 0, the slave's \overline{SS} input must go to its inactive high level between transfers.

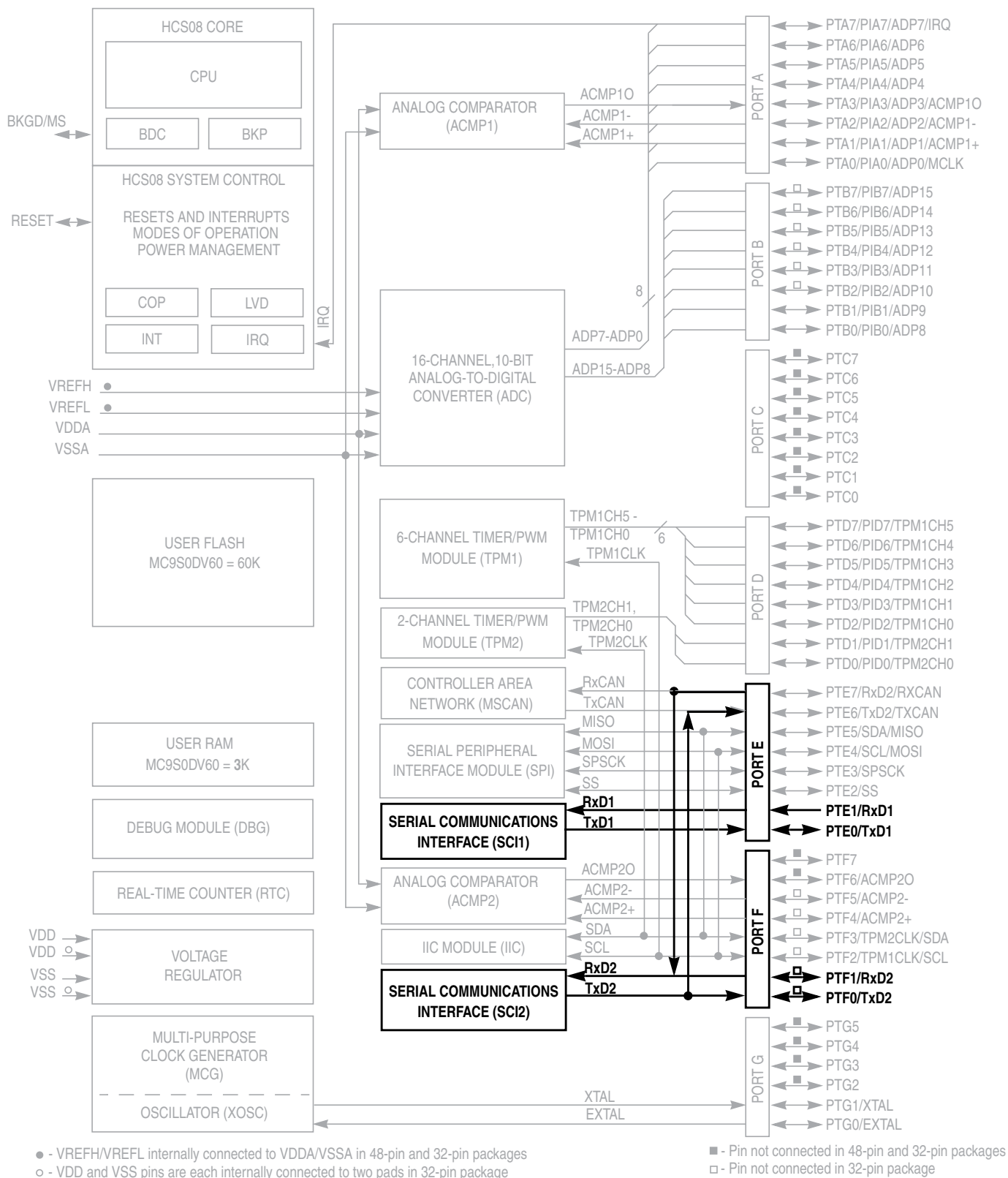


Figure 14-1. MC9S08DV60 Block Diagram

16.1.1 Features

The TPM includes these distinctive features:

- One to eight channels:
 - Each channel may be input capture, output compare, or edge-aligned PWM
 - Rising-Edge, falling-edge, or any-edge input capture trigger
 - Set, clear, or toggle output compare action
 - Selectable polarity on PWM outputs
- Module may be configured for buffered, center-aligned pulse-width-modulation (CPWM) on all channels
- Timer clock source selectable as prescaled bus clock, fixed system clock, or an external clock pin
 - Prescale taps for divide-by 1, 2, 4, 8, 16, 32, 64, or 128
 - Fixed system clock source are synchronized to the bus clock by an on-chip synchronization circuit
 - External clock pin may be shared with any timer channel pin or a separated input pin
- 16-bit free-running or modulo up/down count operation
- Timer system enable
- One interrupt per channel plus terminal count interrupt

16.1.2 Modes of Operation

In general, TPM channels may be independently configured to operate in input capture, output compare, or edge-aligned PWM modes. A control bit allows the whole TPM (all channels) to switch to center-aligned PWM mode. When center-aligned PWM mode is selected, input capture, output compare, and edge-aligned PWM functions are not available on any channels of this TPM module.

When the microcontroller is in active BDM background or BDM foreground mode, the TPM temporarily suspends all counting until the microcontroller returns to normal user operating mode. During stop mode, all system clocks, including the main oscillator, are stopped; therefore, the TPM is effectively disabled until clocks resume. During wait mode, the TPM continues to operate normally. Provided the TPM does not need to produce a real time reference or provide the interrupt source(s) needed to wake the MCU from wait mode, the user can save power by disabling TPM functions before entering wait mode.

- Input capture mode

When a selected edge event occurs on the associated MCU pin, the current value of the 16-bit timer counter is captured into the channel value register and an interrupt flag bit is set. Rising edges, falling edges, any edge, or no edge (disable channel) may be selected as the active edge which triggers the input capture.
- Output compare mode

When the value in the timer counter register matches the channel value register, an interrupt flag bit is set, and a selected output action is forced on the associated MCU pin. The output compare action may be selected to force the pin to zero, force the pin to one, toggle the pin, or ignore the pin (used for software timing functions).

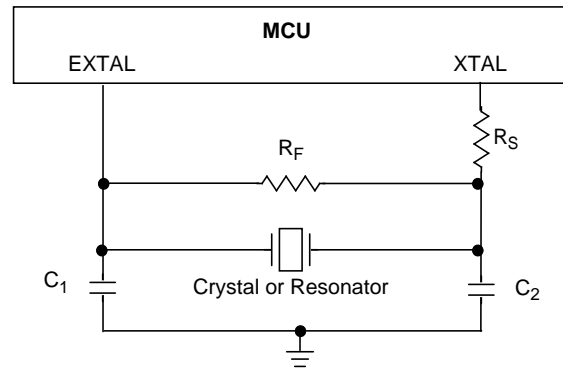
- Edge-aligned PWM mode
The value of a 16-bit modulo register plus 1 sets the period of the PWM output signal. The channel value register sets the duty cycle of the PWM output signal. The user may also choose the polarity of the PWM output signal. Interrupts are available at the end of the period and at the duty-cycle transition point. This type of PWM signal is called edge-aligned because the leading edges of all PWM signals are aligned with the beginning of the period, which is the same for all channels within a TPM.
- Center-aligned PWM mode
Twice the value of a 16-bit modulo register sets the period of the PWM output, and the channel-value register sets the half-duty-cycle duration. The timer counter counts up until it reaches the modulo value and then counts down until it reaches zero. As the count matches the channel value register while counting down, the PWM output becomes active. When the count matches the channel value register while counting up, the PWM output becomes inactive. This type of PWM signal is called center-aligned because the centers of the active duty cycle periods for all channels are aligned with a count value of zero. This type of PWM is required for types of motors used in small appliances.

This is a high-level description only. Detailed descriptions of operating modes are in later sections.

16.1.3 Block Diagram

The TPM uses one input/output (I/O) pin per channel, TPMxCHn (timer channel n) where n is the channel number (1-8). The TPM shares its I/O pins with general purpose I/O port pins (refer to I/O pin descriptions in full-chip specification for the specific chip implementation).

Figure 16-2 shows the TPM structure. The central component of the TPM is the 16-bit counter that can operate as a free-running counter or a modulo up/down counter. The TPM counter (when operating in normal up-counting mode) provides the timing reference for the input capture, output compare, and edge-aligned PWM functions. The timer counter modulo registers, TPMxMODH:TPMxMODL, control the modulo value of the counter (the values 0x0000 or 0xFFFF effectively make the counter free running). Software can read the counter value at any time without affecting the counting sequence. Any write to either half of the TPMxCNT counter resets the counter, regardless of the data value written.



A.11 MCG Specifications

Table A-12. MCG Frequency Specifications (Temperature Range = -40 to 125°C Ambient)

Num	C	Rating	Symbol	Min	Typical	Max	Unit
1	P	Internal reference frequency - factory trimmed at $V_{DD} = 5\text{ V}$ and temperature = 25 °C	f_{int_ft}	—	31.25	—	kHz
2	P	Average internal reference frequency - untrimmed ¹	f_{int_ut}	25	32.7	41.66	kHz
3	P	Average internal reference frequency - user trimmed	f_{int_t}	31.25	—	39.0625	kHz
4	D	Internal reference startup time	t_{irefst}	—	60	100	us
5	—	DCO output frequency range - untrimmed ¹ value provided for reference: $f_{dco_ut} = 1024 \times f_{int_ut}$	f_{dco_ut}	25.6	33.48	42.66	MHz
6	P	DCO output frequency range - trimmed	f_{dco_t}	32	—	40	MHz
7	C	Resolution of trimmed DCO output frequency at fixed voltage and temperature (using FTRIM)	$\Delta f_{dco_res_t}$	—	± 0.1	± 0.2	% f_{dco}
8	C	Resolution of trimmed DCO output frequency at fixed voltage and temperature (not using FTRIM)	$\Delta f_{dco_res_t}$	—	± 0.2	± 0.4	% f_{dco}
9	P	Total deviation of trimmed DCO output frequency over voltage and temperature	Δf_{dco_t}	—	+ 0.5 -1.0	± 2	% f_{dco}
10	C	Total deviation of trimmed DCO output frequency over fixed voltage and temperature range of 0 - 70 °C	Δf_{dco_t}	—	± 0.5	± 1	% f_{dco}
11	C	FLL acquisition time ²	$t_{fl_acquire}$	—	—	1	ms
12	D	PLL acquisition time ³	$t_{pll_acquire}$	—	—	1	ms
13	C	Long term Jitter of DCO output clock (averaged over 2ms interval) ⁴	C_{jitter}	—	0.02	0.2	% f_{dco}
14	D	VCO operating frequency	f_{vco}	7.0	—	55.0	MHz
15	D	PLL reference frequency range	f_{pll_ref}	1.0	—	2.0	MHz
16	T	RMS frequency variation of a single clock cycle measured 2 ms after reference edge. ⁵	$f_{pll_cycjit_2ms}$	—	0.590 ⁴	—	% f_{pll}
17	T	Maximum frequency variation averaged over 2 ms window.	$f_{pll_maxjit_2ms}$	—	0.001	—	% f_{pll}

A.14.1 Radiated Emissions

Microcontroller radiated RF emissions are measured from 150 kHz to 1 GHz using the TEM/GTEM Cell method in accordance with the IEC 61967-2 and SAE J1752/3 standards. The measurement is performed with the microcontroller installed on a custom EMC evaluation board while running specialized EMC test software. The radiated emissions from the microcontroller are measured in a TEM cell in two package orientations (North and East). For more detailed information concerning the evaluation results, conditions and setup, please refer to the EMC Evaluation Report for this device.

The maximum radiated RF emissions of the tested configuration in all orientations are less than or equal to the reported emissions levels.

Table A-18. Radiated Emissions for 3M05C Mask Set

Parameter	Symbol	Conditions	Frequency	f_{osc}/f_{CPU}	Level ¹ (Max)	Unit	
Radiated emissions, electric field — Conditions -	V_{RE_TEM}	$V_{DD} = 5$ $T_A = +25^{\circ}C$ 64 LQFP	0.15 – 50 MHz	16 MHz Crystal 20 MHz Bus	18	dB μ V	
			50 – 150 MHz		18		
			150 – 500 MHz		13		
			500 – 1000 MHz		7		
			IEC Level		L		—
			SAE Level		2		—

¹ Data based on qualification test results.

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